FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	METHOD FOR SELECTIVE ELECTROPLATING OF SEMICONDUCTOR DEVICE I/O PADS USING A TITANIUM-TUNGSTEN SEED LAYER

Application Number :

Date :

First Named Applicant: Tien-Jen Cheng

Attorney Docket Number: FIS920030278US1

TOTAL FEE AUTHORIZED $ 810

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount $	Fee Paid $
Utility Filing Fee	1001	770	770
		Subtotal For Basic Filing Fees: $ 770	

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount $	Fee Paid $
Total Claims : 14	0	1202	18	0
Independent Claims : 2	0	1201	86	0
			Subtotal For Extra Claims Fees: $ 0	

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount $	Fee Paid $
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
				Subtotal For Additional Fees: $40	

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Deposit account number: 090458

Deposit name: IBM Corporation

Deposit authorized name: Sean F. Sullivan

Signature: SFS

Date (YYYYMMDD): 2003-11-18

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.